

WHAT IS CLAIMED IS:

1. A method of making a chip device, the method comprising:  
 providing a bumped die including a plurality of solder bumps thereon;  
 providing a leadframe including source and gate connections;  
 placing the bumped die on the leadframe such that the solder bumps  
 contact the source and gate connections;  
 providing a copper clip;  
 attaching the copper clip to a backside of the bumped die with solder paste  
 such that the coupler clip contacts drain regions of the bumped die and a lead rail; and  
 reflowing the solder paste and solder bumps.

2. A method in accordance with claim 1 wherein the solder paste is  
 placed on the backside of the bumped die prior to attaching the copper clip.

3. A method in accordance with claim 1 wherein the solder paste is  
 placed on the copper clip prior to attaching the copper clip.

4. A method in accordance with claim 1 wherein the solder bumps are  
 reflowed prior to attaching the copper clip.

5. A chip device comprising:  
 a leadframe including source and gate connections;  
 a bumped die including solder bumps on a top side, the bumped die being  
 attached to the leadframe such that the solder bumps contact the source and gate  
 connections; and  
 a copper clip attached to a backside of the bumped die such that the  
 coupler clip contacts drain regions of the bumped die and a lead rail.

6. A chip device in accordance with claim 5 wherein the copper clip  
 is attached to the bumped die with solder paste.

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